

Vítejte na O-leaderu

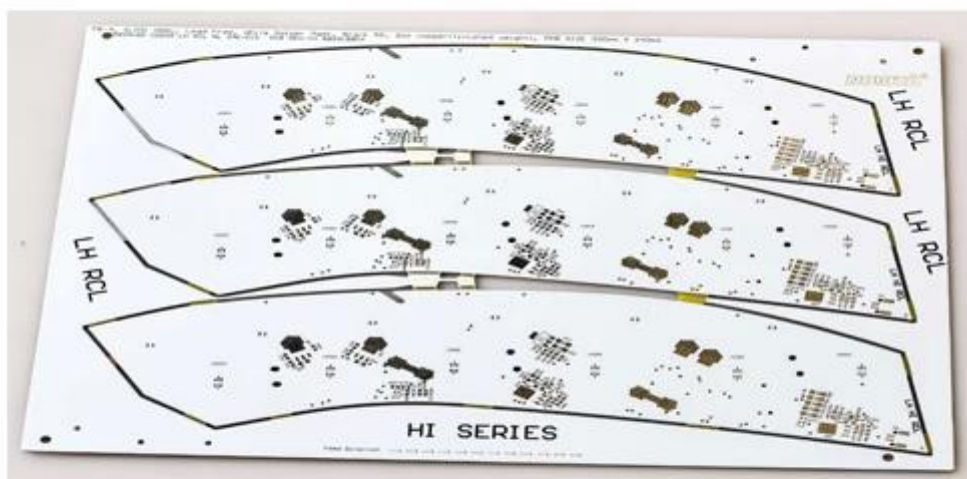
Společnost O-Leading se snaží být vaším partnerem pro řešení na jednom místě v dodavatelském řetězci EMS, včetně návrhu PCB, výroby PCB a montáže PCB (PCBA). Poskytujeme některé z nejpokročilejších technologií PCB, včetně HDI PCB, vícevrstvých PCB, pevných PCB . Můžeme podporovat od rychlého otočení prototypu po střední a hromadnou výrobu. ([Výrobce DPS](#))

Naši globální zákazníci jsou obecně našimi službami velmi ohromeni: rychlá odezva, konkurenceschopná cena a závazek kvality. Poskytování cennějších technických služeb a celkového řešení je cesta vedoucí k O.

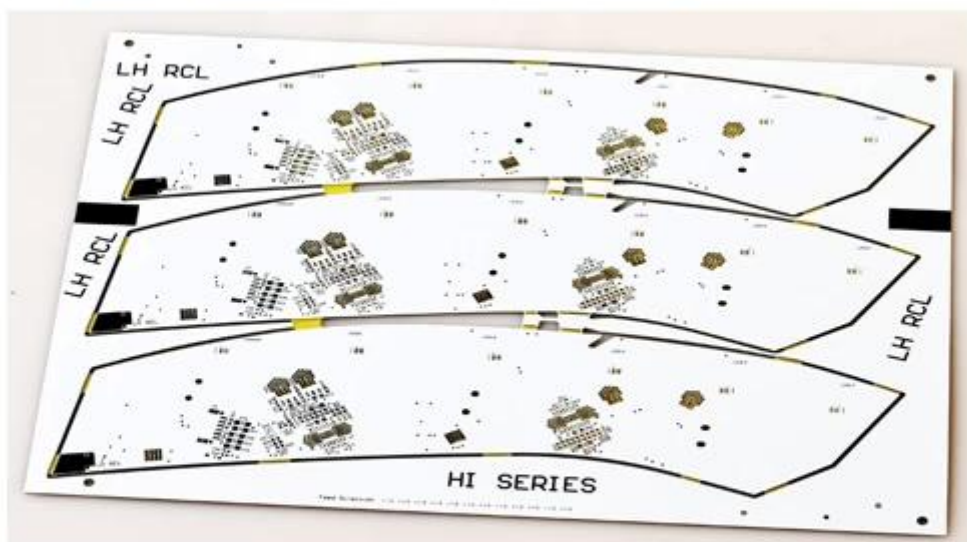
Při pohledu do budoucnosti se O-leader soustředí na inovace a vývoj technologie výroby elektroniky jako vždy a vytrvale usiluje o jednorázovou službu PCB a PCBA, aby poskytoval prvotřídní služby a vytvářel větší hodnotu pro naše zákazníky. ([Výrobce desek plošných spojů OEM](#))

Popis výrobku

Místo původu	Guang dong, Čína (pevnina)	Jméno značky	O-vedoucí
Základní materiál	FR-4, hliník, Rogers, těžká měď atd.	Tloušťka mědi	0,5oz-5oz
Min. Velikost otvoru	0,2 mm	Min. Šířka čáry	0,2 mm
Povrchová úprava	Ponoření zlato / cín / stříbro, OSP, HASL bez obsahu olova	Tloušťka desky	0,1 - 5 mm
použitelné pro	led, mobilní telefon, klimatizace, pračky	charakter	Průmyslová kontrola pcb
certifikáty	ISO9001, UL, RoHS, SGS	Q / CTN	požadavek klienta
hmotnost	0,01 kg -5 kg	MOQ	10ks
barva	modrá, červená, zelená, černá	Min. Řádkování	0,2 mm
Modelové číslo	pcb montáž pcba výrobce	cena	0,1-10 \$
tupý typ	Client požadavek	velikost	0,01 m3 - 10 m3



www.o-leading.com



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Náš tým



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



Certifikace





No. SZXEC1900530401

Date: 30 Mar 2019

Page 1 of 6

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313, FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PDBEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory



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REV. 08/2007 Page 6

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No. SZXEC1900530401

Date: 30 Mar 2019

Page 2 of 6

Test Results :

Test Part Description:

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green™PCB

Remarks :

(1) $1 \text{ mg/kg} = 1 \text{ ppm} = 0.0001\%$

(2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Q27
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tri bromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tri bromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max	Max					
	Min	Min			Area	Solder	Oper	Meets	C		
	Edge	Thk			Diam	Limits	Temp	Flame	UL796	T	
mm(in)	mm(in)			mm(in)	C	sec	C	Class	DSR	I	
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲	*
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Schopnost procesu

Schopnosti výroby PCB

Počet vrstev: 1Layer-32Layer

Konečná tloušťka mědi □ 1 / 3oz-12oz

Min Šířka / mezera interní internal 3,0 mil / 3,0 mil

Min Šířka / rozteč linek externí: 4,0 mil / 4,0 mil

Maximální poměr stran: 10: 1

Tloušťka desky □ 0,2 mm - 5,0 mm

Maximální velikost panelu (palce): 635 x 1500 mm

Minimální velikost vrtané díry: 4 mil

Tolerance plated Hole: +/- 3mil

Blind / Buried Vias (typy AII): ANO

Prostřednictvím výplně (vodivé, nevodivé): ANO

Základní materiál: FR-4, FR-4high Tg.Halogenový materiál, Rogers, Hliníková základna,Polyimid,

Těžká měď

Povrchové úpravy: HASL, OSP, ENIG, HAL-LF, Immersion silver,Immersion Cín, Zlaté prsty, Uhlíkový inkoust

Výrobní schopnosti SMT

Materiál DPS: FR-4, CEM-1, CEM-3, deska na bázi hliníku

Maximální velikost DPS: 510 x 460 mm

Minimální velikost DPS □ 50x50 mm

Tloušťka DPS □ 0,5 mm - 4,5 mm

Tloušťka desky □ 0,5-4 mm

Minimální velikost komponent: 0201

Standardní součást velikosti čipu: 0603 a větší

Maximální výška komponenty □ 15 mm

Min. Stoupání olova: 0,3 mm

Min. Rozteč kuliček BGA: 0,4 mm

Přesnost umístění: +/- 0,03 mm